



## SOLDER-PASTE TACKINESS TESTER TK-1S



### Features

- Measure the adhesive strength of materials such as solder paste. Measurement items: Tackiness, Load and Insertion Depth
- There are three insertion methods, making it possible to measure under the conditions closer to the actual mounting manner.
- It is useful to feed back the difference of the tackiness obtained by changing the set conditions to the production site in a timely manner.

### Product specification

Item		Specification
Model Name		TK-1S
Load Sensor	Range	0 - 400gf +/-2gf

	Resolution	0.25gf
Measurement Methods		(1) Continuous preload, JIS (2) Insertion depth (3) Point preload, IPC
Parameters Measured		(1) Tackiness: T gf (2) Real Preload: P gf (3) Real Insert depth: D $\mu$ m
Preset Ranges		(1) Preload : -20 - -400gf (2) Time : 0.1 - 99.9s (3) Speed : 1.0 - 10.0mm/s (Continuous preload / Insertion depth) 2.0 - 600.0mm/min (Point preload) (4) Depth : 20 - 200 $\mu$ m * (5) Temperature : Room temp. +10C - 250C
Accessories		● Hand printer with 0.2 mm mask ● Test piece, 5.1 -mm dia. probe
Outputs	Digital	RS232C
Weight		Approx. 10kg

\* In the testing method with continuous loading insertion speed is setting value until Retraction speed 120mm/min. and over 120mm/min, insertion speed is 120mm/min.

\* The above specifications are subject to change without notice.